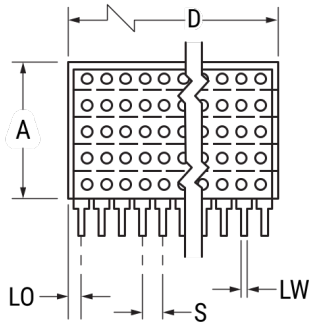
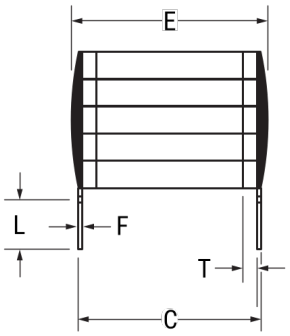
L1WN30C395KS24

KPS LDD Comm SMPS, Ceramic, 3.9 uF, 10%, 500 VDC, X7R, N/A

Side View



End View



Click here for the 3D model.

General Information	
Series	KPS LDD Comm SMPS
Style	Leaded Stacked Chip
Description	Low ESR, High Current Stacked Ceramic Chips
Features	Low ESR, High Current, High Performance
RoHS	No
Prop 65	⚠ **WARNING:** Cancer and reproductive harm - http://www.p65warnings.ca.gov.
Termination	60/40 Solder Coated
Lead	Wire Leads
Failure Rate	N/A
Testing and Reliability	Commercial
AEC-Q200	No
Notes	Note: Number of chips in stack depends on design. Number of Chips in this stack = 2. Note: Lead alignment within pin rows shall be within ±.0.13 mm.

Dimensions	
D	25.715mm +/-1.585mm
L	6.35mm MIN
T	1.397mm MAX
S	2.54mm TYP
F	0.254mm +/-0.051mm
A	6.096mm MAX
C	11.43mm +/-0.635mm
E	12.7mm NOM
G	1.4mm +/-0.25mm
LO	1.586mm MAX
LW	0.508mm +/-0.051mm

Specifications	
Capacitance	3.9 uF
Capacitance Tolerance	10%
Voltage DC	500 VDC
Dielectric Withstanding Voltage	750 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Dissipation Factor	2.5% 1 kHz 25C
Aging Rate	3% Loss/Decade Hour
Insulation Resistance	25.6 GOhms

Packaging Specifications	
Packaging	Waffle, Box
Packaging Quantity	28